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DIALOG(R) File 351:Derwent WPI

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WPI Acc No: 1996-232976/199624

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Baked wafer biscuits contg. no sugar - contain dry ingredients, dextrose, starch, corn flower, egg, fat, emulsifier, salt, milk and/or soya powder, spices and water

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Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
HU 70252	T	19950928	HU 94106	A	19940114	199624 B
HU 214189	B	19980128	HU 94106	A	19940114	199825

Priority Applications (No Type Date): HU 94106 A 19940114

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
HU 214189	B		A21D-013/08	Previous Publ. patent HU 70252
HU 70252	T		A21D-013/08	

Abstract (Basic): HU 70252 T

Raw wafer mix comprises (wt./wt.%): 10-28 dry ingredients, 30-50 dextrose, 35-55 powder or liq. starch syrup, corn flour without amylase, 0.2-3 egg powder or egg white concentrate, 1-4 fats, 0.05-2.0 emulsifiers, 1-5 salt, 1-4 milk powder and/or soya powder, 0.5-10 spices and water to 100.

Title Terms: BAKE; WAFER; BISCUIT; CONTAIN; NO; SUGAR; CONTAIN; DRY; INGREDIENT; DEXTROSE; STARCH; CORN; FLOWER; EGG; FAT; EMULSION; SALT; MILK; SOY; POWDER; SPICE; WATER

Derwent Class: D11

International Patent Class (Main): A21D-013/08

File Segment: CPI

Manual Codes (CPI/A-N): D01-B02C

Derwent Registry Numbers: 0038-U

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